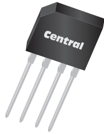
Material Composition Specification

Case B-M



Device average mass . . . . **1.5 g**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.51%	7.68	Si	7440-21-3	0.51%	7.68	5,120
leadframe	Cu alloy	44.54%	668.07	Cu	7440-50-8	44.49%	667.4	444,933
				Fe	7439-89-6	0.04%	0.67	447
die attach	high temperature solder	0.99%	14.78	Pb	7439-92-1	0.91%	13.67	9,113
				Sn	7440-31-5	0.05%	0.74	493
				Ag	7440-22-4	0.02%	0.37	247
encapsulation*	EMC	53.93%	809	silica	7631-86-9	29.47%	442	294,667
				brominated epoxy resin	Proprietary	22.22%	333.33	222,220
				Sb_2O_3	1309-64-4	2.24%	33.67	22,447
	EMC GREEN	53.93%	809	silica	7631-86-9	47.73%	715.97	477,313
				phenol resin	9003-35-4	4.31%	64.72	43,147
				zinc borate	1332-07-6	1.62%	24.27	16,180
				carbon black	1333-86-4	0.27%	4.04	2,693
plating**	tin/lead process	0.031%	0.47	Sn	7440-31-5	0.006%	0.094	63
				Pb	7439-92-1	0.025%	0.376	251
	matte tin	0.031%	0.47	Sn	7440-31-5	0.031%	0.47	313

*EMC GREEN molding compound is Halogen-Free.

**For Lead Free plating, add suffix “PB FREE” to part number.
For Tin/Lead plating, add suffix “TIN/LEAD” to part number.
No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.